# Advance Information

## **Power MOSFET**

-60 V, 7.7 m $\Omega$ , -100 A, Single P-Channel



### ON Semiconductor®

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#### **Features**

- Small Footprint (5 × 6 mm) for Compact Design
- Low R<sub>DS</sub>(on) to Minimize Conduction Losses
- NVMFS5A160PLZWF :

Wettable Flank Option for Enhanced Optical Inspection

- AEC-Q101 Qualified and PPAP Capable
- Pb-Free and RoHS compliance

# $V_{DSS}$ $R_{DS}$ (on) Max $I_{D Max}$ -60 V 7.7 mΩ @ -10 V 10.5 mΩ @ -4.5 V -100 A

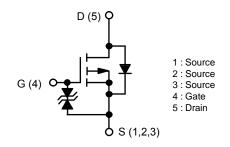
#### **SPECIFICATIONS**

**ABSOLUTE MAXIMUM RATINGS** at Tj = 25°C unless otherwise noted

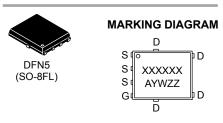
(Notes 1, 2, 3, 4)

Parameter			Symbol	Value	Unit
Drain to Source Voltage			$V_{DSS}$	-60	V
Gate to Source Voltage			$V_{GS}$	±20	V
Continuous Drain Current <sup>R</sup> θJC (Notes 2, 4)	Steady State	T <sub>C</sub> = 25°C	ΙD	-100	Α
Power Dissipation R <sub>θ</sub> JC (Note 2)	State	T <sub>C</sub> = 25°C	PD	200	W
Continuous Drain Current R <sub>θ</sub> JA (Notes 2, 3, 4)	Steady State	T <sub>A</sub> = 25°C	I <sub>D</sub>	-15	Α
Power Dissipation R <sub>θ</sub> J <sub>A</sub> (Notes 2, 3)	Otato	T <sub>A</sub> = 25°C	$P_{D}$	3.8	W
Pulsed Drain Current	PW ≤ 10 μs, duty cycle ≤ 1%		I <sub>DP</sub>	-400	Α
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode)			IS	-100	Α
Single Pulse Drain to Source Avalanche Energy (L = 1.0 mH, $I_{L(pk)}$ = -26 A)			E <sub>AS</sub>	335	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		TL	260	°C	

#### **ELECTRICAL CONNECTION**



#### **P-Channel MOSFET**



XXXXXX= Specific Device Code 5A160L(NVMFS5A160PLZ) 160LWF(NVMFS5A160PLZWF)

A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction to Case Steady State	$R_{\theta JC}$	0.75	°C/W
Junction to Ambient Steady State (Note 3)	$R_{\theta JA}$	39	-0/00

Note 1 : Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Note 2 : The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted

Note 3: Surface mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.

Note 4: Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

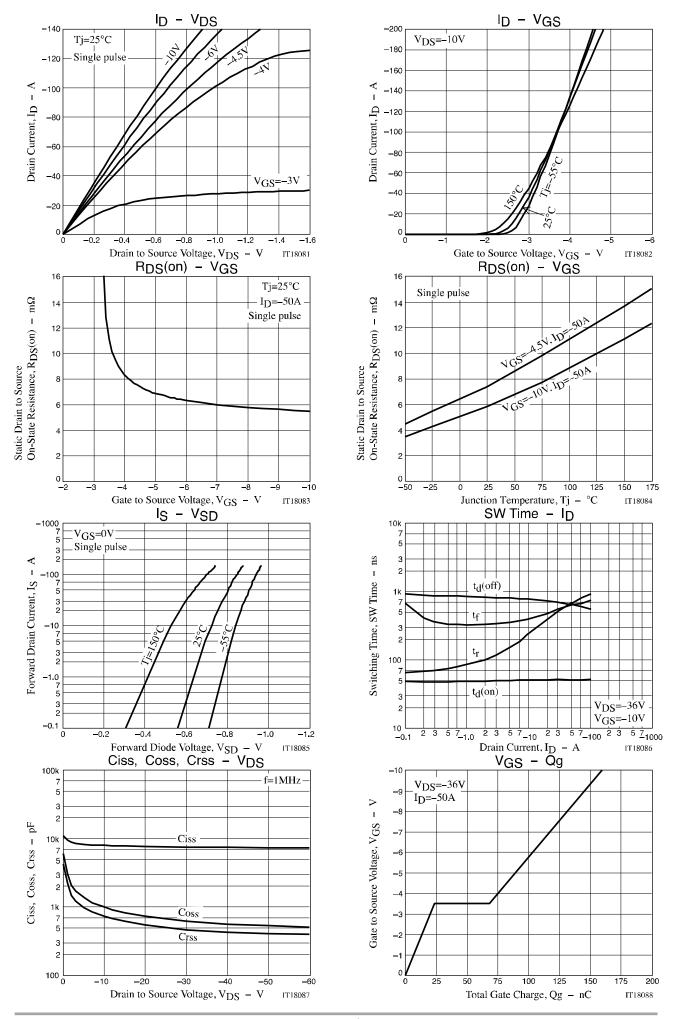
This document contains information on a new product. Specifications and information herein are subject to change without notice.

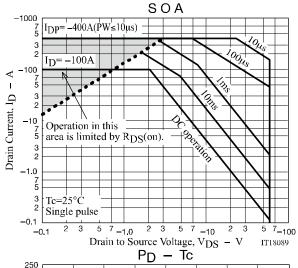
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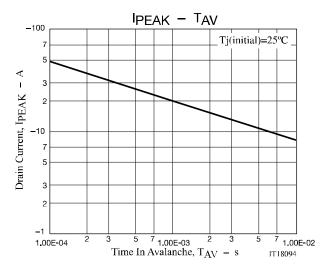
**ELECTRICAL CHARACTERISTICS** at TJ = 25°C unless otherwise specified (Note 5)

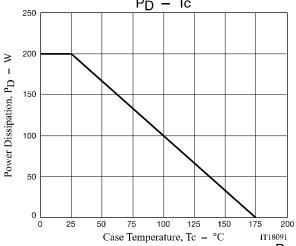
Parameter	Symbol	Conditions -		Value			Unit
Parameter	Symbol			min	typ	max	Onit
OFF CHARACTERISTICS		•	•				
Drain to Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> =	–1 mA	-60			>
Zero-Gate Voltage Drain Current	IDSS	$V_{GS} = 0 V$				-1.0	μΑ
Zero-Gate Voltage Brain Gurrent	יטפט	V <sub>DS</sub> = -60 V	T <sub>J</sub> = 100°C			-100	μΑ
Gate to Source Leakage Current	IGSS	$V_{GS} = \pm 16 \text{ V}, V_{D}$	OS = 0 V			±10	μΑ
<b>ON CHARACTERISTICS</b> (Not	e 6)						
Gate Threshold Voltage	V <sub>GS</sub> (th)	$V_{DS} = -10 \text{ V}, I_{D}$	= -1 mA	-1.2		-2.6	V
Drain to Source On Resistance	R <sub>DS</sub> (on)	$V_{GS} = -10 \text{ V}$			5.8	7.7	mΩ
	TVDS(OII)	$V_{GS} = -4.5 \text{ V}$	I <sub>D</sub> = -50 A		7.3	10.5	mΩ
Forward Transconductance	9FS	$V_{DS} = -10 \text{ V}, I_{D}$	= -50 A		125		S
CHARGES, CAPACITANCES	& GATE RE	SISTANCE					
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = -20 V			7,700		pF
Output Capacitance	C <sub>oss</sub>				720		
Reverse Transfer Capacitance	C <sub>rss</sub>				540		
Total Gate Charge	Qg(tot)	V <sub>GS</sub> = -10 V, V <sub>DS</sub> = -36 V, I <sub>D</sub> = -50 A			160		
Gate to Source Charge	Q <sub>gs</sub>				24		nC
Gate to Drain Charge	Q <sub>gd</sub>				45		
SWITCHING CHARACTERIS	TICS (Note 7)						
Turn-ON Delay Time	t <sub>d</sub> (on)				50		
Rise Time	t <sub>r</sub>	$V_{GS} = -10 \text{ V}, V_{D}$	<sub>OS</sub> = -36 V,		690		
Turn-Off Delay Time	t <sub>d</sub> (off)	I <sub>D</sub> = -50 A, R <sub>G</sub> =	$I_D = -50 \text{ A}, R_G = 50 \Omega$		645		ns
Fall Time	tf				643		
DRAIN SOURCE DIODE CHA	RACTERIST	ics	· · · · · · · · · · · · · · · · · · ·	Į			
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = 0 V, I <sub>S</sub> =	–50 A		-0.83	-1.5	V
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0 V, di/dt$	= 100 A/μs,		93		ns
Reverse Recovery Charge	Q <sub>rr</sub>	$I_S = -50 \text{ A}$			218		nC

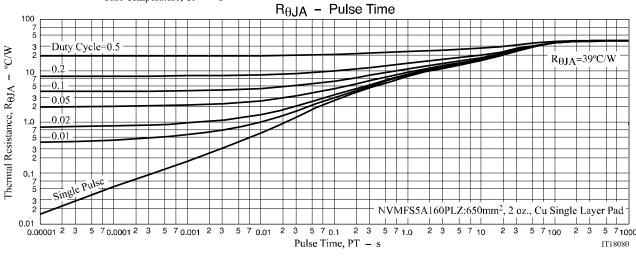
Note 5 : Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. Note 6 : Pulse Test: pulse width  $\leq 300~\mu s$ , duty cycle  $\leq 2\%$ . Note 7 : Switching characteristics are independent of operating junction temperatures.











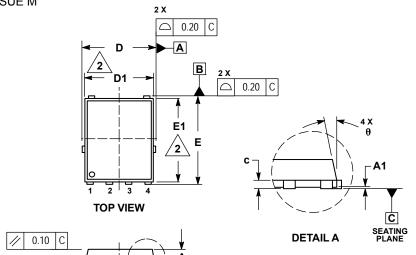
#### **PACKAGE DIMENSIONS**

unit: mm

#### DFN5 5x6, 1.27P (SO-8FL)

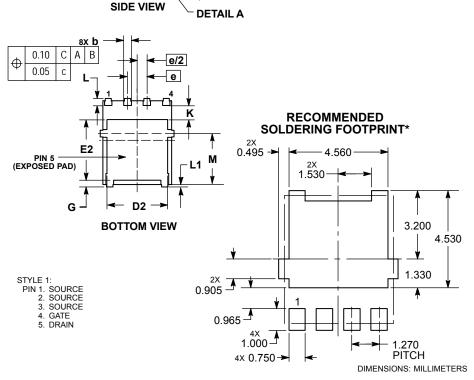
0.10 C

CASE 488AA **ISSUE M** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.90	1.00	1.10		
A1	0.00	-	0.05		
b	0.33	0.41	0.51		
С	0.23	0.28	0.33		
D	5.00	5.15	5.30		
D1	4.70	4.90	5.10		
D2	3.80	4.00	4.20		
Е	6.00	6.15	6.30		
E1	5.70	5.90	6.10		
E2	3.45	3.65	3.85		
е	1.27 BSC				
G	0.51	0.575	0.71		
K	1.20	1.35	1.50		
L	0.51	0.575	0.71		
L1	0.125 REF				
М	3.00	3.40	3.80		
θ	0 °		12 °		



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing)
NVMFS5A160PLZT1G	5A160L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	1,500 / Tape & Reel
NVMFS5A160PLZWFT1G	160LWF	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free, Wettable Flanks)	1,500 / Tape & Reel
NVMFS5A160PLZT3G	5A160L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	F 000 / Tone & Deel
NVMFS5A160PLZWFT3G	160LWF	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free, Wettable Flanks)	5,000 / Tape & Reel

<sup>†</sup> For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub\_link/Collateral/BRD8011-D.PDF

Note on usage: Since the NVMFS5A160PLZ is a MOSFET product, please avoid using this device in the vicinity of highly charged objects. Please contact sales for use except the designated application.

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